

CLAIMS

1. A solid-state imaging apparatus comprising:
 - a solid-state imaging element, having an energy ray sensitive portion;
 - 5 a signal processing circuits, processing signals output from said solid-state imaging element; and
 - a package, housing the solid-state imaging element and the signal processing circuit,
 - wherein the signal processing circuit is positioned at a planar portion of the package that differ from a planar portion at which the solid-state imaging element is positioned.
- 10 2. A solid-state imaging apparatus comprising:
 - a solid-state imaging element, having an energy ray sensitive portion;
 - 15 a signal processing circuit, processing signals output from the solid-state imaging element; and
 - a package, housing the solid-state imaging element and the signal processing circuit,
 - wherein the package has a first planar portion and a second planar portion, formed to be stepped with respect to the first planar portion, and
 - 20 wherein the solid-state imaging element is positioned at the first planar portion, and the signal processing circuit is positioned at the second planar portion.
- 25 3. The solid-state imaging apparatus according to Claim 1 or 2, wherein the signal processing circuit includes a load resistor that is

electrically connected to an output terminal of the solid-state imaging element.

4. The solid-state imaging apparatus according to Claim 1 or 2, wherein the signal processing circuit comprises:

5 a load resistor, one end of which is electrically connected to an output terminal of the solid-state imaging element and the other end of which is grounded; and

a buffer amplifier, having a bipolar transistor that is electrically connected to the output terminal of the solid-state imaging element.